BB02-BY - 1.27mm x 1.27mm (0.05 x 0.05) BOX HEADER, SMD, DUAL ROW - 10 TO 100 CONTACTS

SPECIFICATIONS:
- CURRENT RATING: 1 AMP
- INSULATOR RESISTANCE: 1000 MEGOHMS MIN.
- DIELECTRIC WITHSTANDING: AC 300 V
- CONTACT RESISTANCE: 20m OHMS MAX.
- OPERATING TEMPERATURE: -40°C TO +105°C
- CONTACT MATERIAL: BRASS
- INSULATOR MATERIAL: THERMOPLASTIC, UL 94V-0
- PLATING: GOLD OR TIN OVER 30-50U" NICKEL
- SOLDERABILITY: IR REFLOW: 280°C FOR 10 SEC
- MANUAL SOLDER: 380°C FOR 3-5 SEC

MAKES WITH:
- PERFECT MATING PARTS: BB02-CM, BB02-CU
- OTHER MATING PARTS: BB02-CL, BB02-CN (4.40MM PROFILE ONLY)

NOTES:
1. MATING HEIGHTS:
   a. WITH INSULATION HEIGHT OF Δ=5.7MM, THE
      MATE HEIGHT IS 2.0MM SOCKET HEIGHT.
   b. WITH INSULATION HEIGHT OF B=7.3MM, THE
      MATE HEIGHT IS 3.6MM SOCKET HEIGHT.

Recommended PCB BOARD SMD LAYOUT
(TOLERANCE: ±0.05)

HOW TO ORDER

BB02 - BY XXX1 - XXX - X00000

NO. OF CONTACTS:
10 TO 98
100 Contacts = 00

CONTACT PLATING OPTIONS:
- K = GOLD FLASH (STANDARD)
- A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- T = BRIGHT TIN
- M = MATT TIN

"H" HEIGHT OPTIONS:
- 3 = TUBE
- 5 = TUBE & CAP
- 6 = TAPE & REEL
- 8 = TAPE & REEL & CAP

PACKAGING OPTIONS:
- A = WITH PEG
- B = WITHOUT PEG

LOCATING PEG OPTIONS:

Scale: 1:1
THIRD ANGLE
Material: SEE NOTE

DRAWN: TMC
DATE: 3 NOV. 15
REVISION: 1
UNIT: mm

Type: BB02-BY

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